

EMB-BSW2

Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation <p style="margin-left: 20px;">Comment: There are 2 temperature points marginal passed but function are stable.</p>			
Test Result Summary				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	2
Defect Unsolved	0	0	0	2

Issue date	QE Manager	Test Engineer
2017 / 12 / 13	KJ Wang	Jerry Chen

Sample Configuration & Quantity Under Test

- **Model name : EMB-BSW2**
- **M/B Name : EMB-BSW2 / Rev. 1.01**
- **CPU : Intel Pentium N3710 / 1.60GHz**
- **BIOS : R1.0 (EBW2AM10) (11/20/2017)**
- **Chipset: Intel Braswell**
- **Memory : Innodisk DDR3L 1600 8GB x 1 / Memory chipset: SEC K4B4G0846D**
- **2.5" SATA HDD: HGST 500GB / HTS725050A7E630**
- **Test Software : Windows 10 / Run PassMark Burn In Test 8.1 Pro**
- **Power Supply: Zippy / HG2-6400P / 400W (MAX)**
- **Heat Sink:**

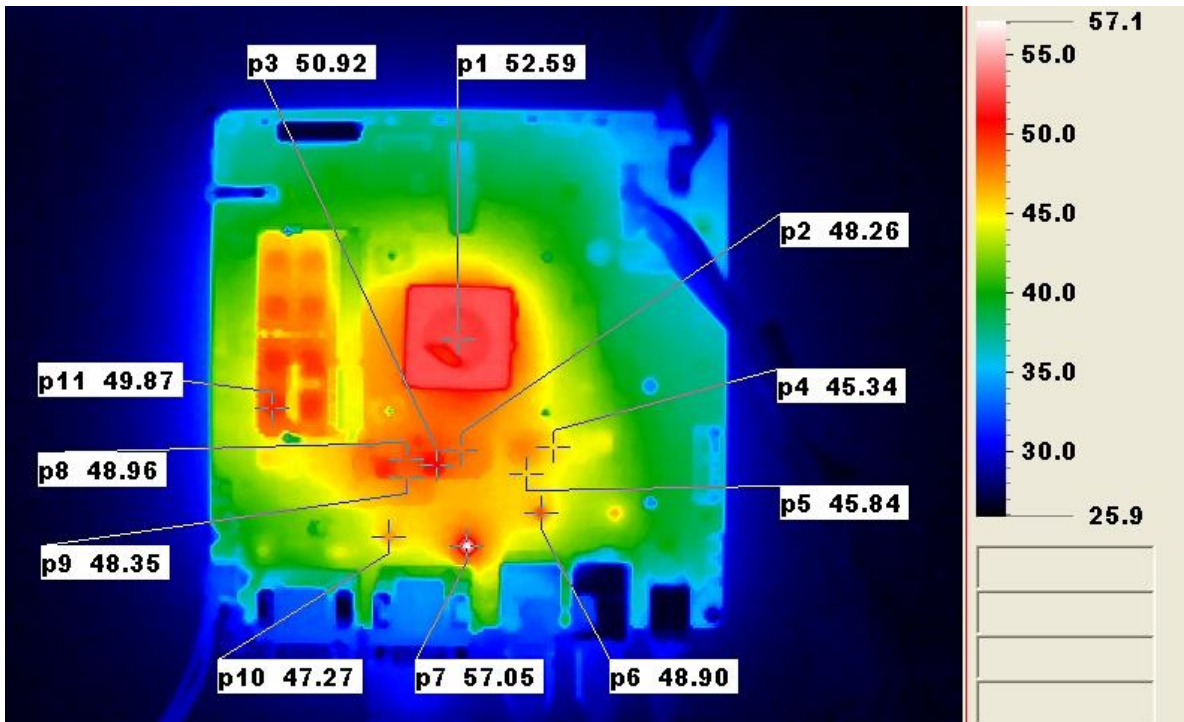


Thermal Image Analysis

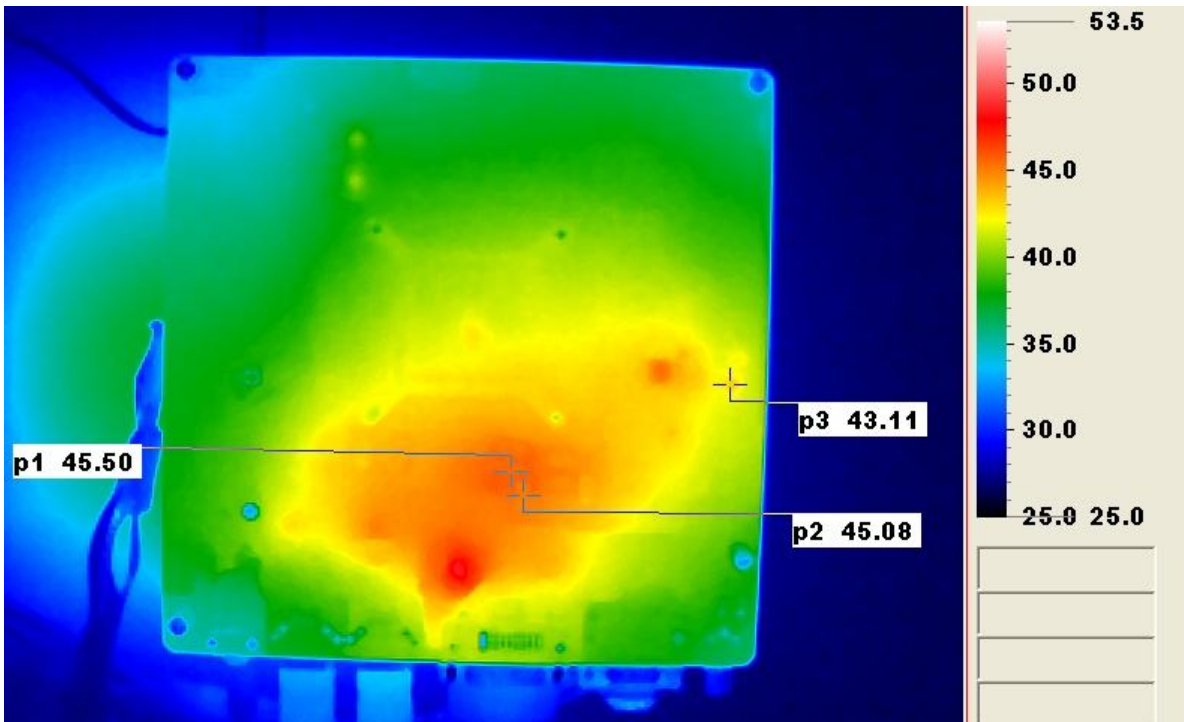
1. Test Date: 2017-12-11
2. Test Product: EMB-BSW2
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 20 Channel Thermal Recorder:
 - 4.1.1 OMRON Inc,
 - 4.2.2 Model: ZR-RX45
Date of Calibration: 12/20/2016
Due date of Calibration: 12/19/2017
Serial Number: H30481978
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
Date of Calibration: 11/23/2017
Due date of Calibration: 11/22/2018
Serial Number: 1051444
5. Test Condition:
Test by DA-100: 25.0°C with Heat Sink
6. Take Picture Time:
After power on 2 hours

Temperature Profile Test:

Front Side:



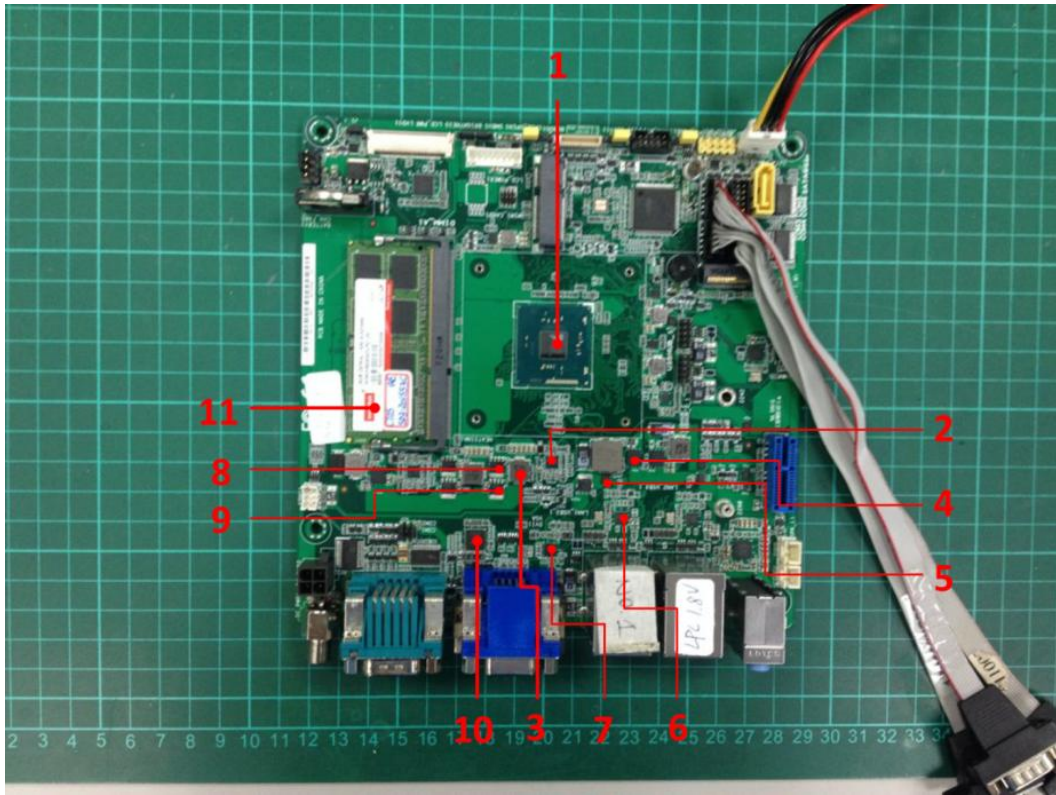
Rear Side:



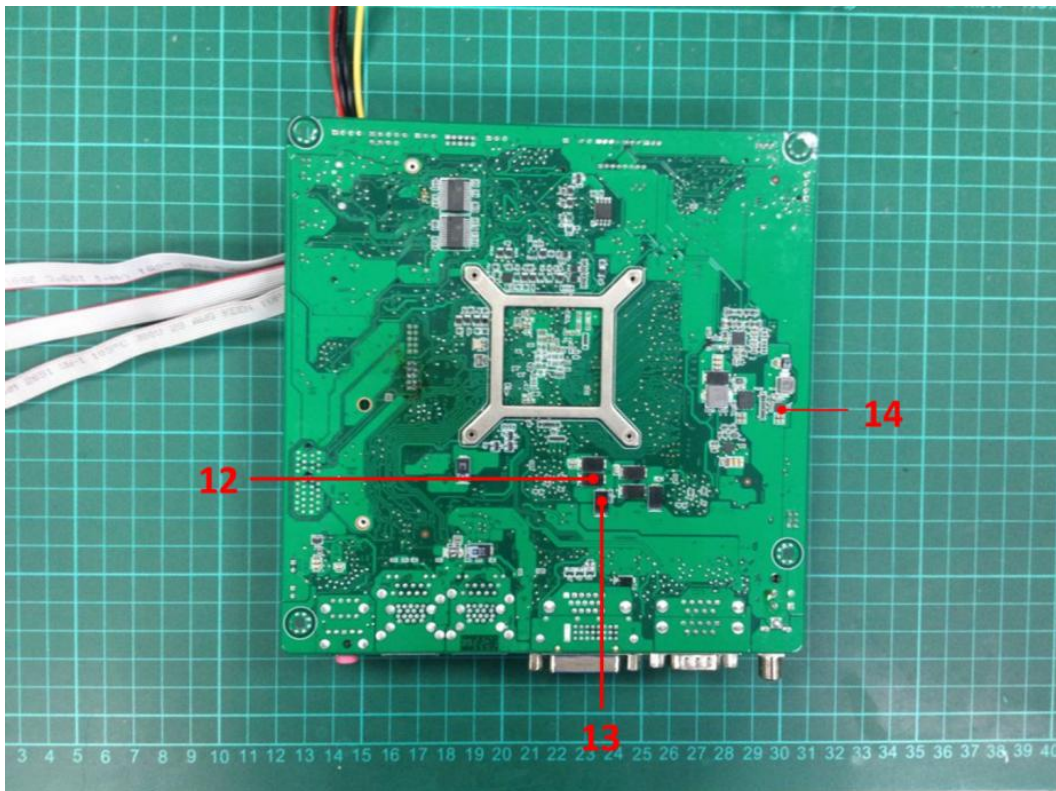
Terminal Recorder:

Measuring Thermal Couple Position :

Front Side:



Rear Side:



Using YOKOGAWA Inc / DA100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2) TPT(*3)		Note
				25°C	50°C	
1	U1	Intel Pentium N3710 / 1.60GHz	90	67.1	92.1	Note 4
2	PU9	PWM CONTROLLER RT8161BGQW	125	54.2	79.2	
3	PL10	INDUCTOR 0.36UH/24A 20	125	57.6	82.6	
4	PQ1	DUAL N-MOSFET EMB06K03HP	125	49.6	74.6	
5	Q19	N-MOSFET QM0930M3	125	49.8	74.8	
6	LAN1	C.S RTL8111G-CG QFN-32	100	51	76	
7	GVU1	BRIDGE IT6516BFN/BX-0062	100	60.6	85.6	
8	PQ24	N-MOSFET PH4030DLVX SOT669	150	54.7	79.7	
9	PQ23	N-MOSFET PH4030DLVX SOT669	150	51.6	76.6	
10	DU1	C.S ASM1442K (A1) QFN-48	85	51.5	76.5	Note 4
11	Memory	Memory chipset	95	52.4	77.4	
12	PCE10	CAP PL 15UF/25V (7343/D) 20%	105	54.4	79.4	
13	PCE11	PL EL 470UF/2V (7343/D) 20%	105	52.6	77.6	
14	PU4	DOWN CONVERTER NB671GQ-Z	125	47.7	72.7	
15	Air	Air temperature	N/A	25	50	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "TAT" indicates the actual measured temperature under 25°C working environmental.
- "TPT" indicates the predicted temperature under product specification.
- Judgment Criteria:**
 - Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.
- RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
- Defect NO. : [BUL1703LABD01](#)